



METECH INTERNATIONAL LIMITED
(Company Registration No.: 199206445M)
(Incorporated in the Republic of Singapore)

PARTIAL REDEMPTION OF BOND ISSUE

*Unless otherwise defined, all capitalised terms and references used in this announcement shall have the same meanings ascribed to them in the Announcements dated 4 October 2016, 23 November 2016, 29 November 2016 and 9 December 2016 (the "**Previous Announcements**").*

The Board of Directors (the "**Board**") of Metech International Limited (the "**Company**") refers to the Company's Previous Announcements with regards to the issue of Listco Bonds for a sum of S\$2 million through the crowdfunding platform of FundedHere Pte Ltd.

The Board wishes to announce that the Company has in accordance with the Loan Agreement returned 50% of the Principal as scheduled to the accredited investors. The sum of S\$1 million, together with the interest due on 13 December 2017, were disbursed to accredited investors today.

The Company will update shareholders on any material developments in relation to the Bond Issue.

By Order of the Board
METECH INTERNATIONAL LIMITED

Andrew Eng
Chief Executive Officer
13 December 2017

*This announcement has been prepared by the Company and its contents have been reviewed by the Company's sponsor, RHT Capital Pte. Ltd. (the "**Sponsor**") for compliance with the relevant rules of the Singapore Exchange Securities Trading Limited (the "**SGX-ST**"). The Sponsor has not independently verified the contents of this announcement.*

This announcement has not been examined or approved by the SGX-ST and the SGX-ST assumes no responsibility for the contents of this announcement, including the correctness of any of the statements or opinions made or reports contained in this announcement.

The contact person for the Sponsor is Mr Mah How Soon, Registered Professional, RHT Capital Pte. Ltd., 9 Raffles Place #29-01, Republic Plaza Tower 1 Singapore 048619, telephone (65) 6381 6757.